

What is Claimed is:

- 1. A method for detecting defects in a reticle used in integrated circuit chip fabrication, said method comprising:
 - (a) obtaining digital image data corresponding to an image of a reticle;
- (b) processing the digital image data according to predetermined criteria to identify defects; and
 - (c) simulating a response that would be produced if the reticle were to be utilized in a photolithographic system, by processing the digital image data corresponding to the reticle.
 - 2. A method according to Claim 1, wherein the digital image data are obtained by scanning the reticle.
 - 3. A method according to Claim 1, wherein the defects are identified in step (b) by comparing the digital image data to reference digital image data.
 - 4. A method according to Claim 1, wherein step (c) simulates an aerial image which would be produced by the reticle.
 - 5. A method according to Claim 1, further comprising a step of categorizing defects based on simulation results produced in step (c).
 - 6. A method according to Claim 1, wherein the digital image data are in raster format.
 - 7. A method according to Claim 1, further comprising a step of modifying a format of the digital image data prior to performing step (c).

- 8. A method according to Claim 1, further comprising a step of providing a reference simulation for comparison to a simulation produced in step (c).
- 9. A method for detecting defects in a reticle used in integrated circuit chip fabrication, said method comprising:
 - (a) obtaining digital image data corresponding to an image of a reticle;
- (b) processing the digital image data according to predetermined criteria toidentify defects;
 - (c) specifying a window around one of the defects identified in step (b); and
 - (d) simulating a response that would be produced if the window specified in step (c) were to be utilized in a photolithographic system, by processing digital image data corresponding to the window specified in step (c).
 - 10. A method according to Claim 9, wherein the digital image data are obtained by scanning the reticle.
 - 11. A method according to Claim 9, wherein step (d) simulates an aerial image which would be produced by the window.
 - 12. A method according to Claim 9, further comprising a step of categorizing defects based on simulation results produced in step (d).
 - 13. A method according to Claim 9, further comprising a step of simulating a window of corresponding reference image data for comparison to simulation results produced in step (d).
 - 14. A method according to Claim 9, wherein the window is 64 x 64 pixels.
 - 15. A method according to Claim 9, wherein the digital image data processed in step (d) are grayscale data.

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- 16. A method according to Claim 9, wherein the defects are identified in step (b) by comparing the digital image data to reference digital image data.
- 17. An apparatus comprising a computer readable medium having encoded thereon computer-executable process steps, said process steps for detecting defects in a reticle used in integrated circuit chip fabrication, wherein said process steps comprise steps to:
 - (a) obtain digital image data corresponding to an image of a reticle;
 - (b) process the digital image data according to predetermined criteria to identify defects; and
 - (c) simulate a response that would be produced if the reticle were to be utilized in a photolithographic system, by processing the digital image data corresponding to the reticle.
 - 18. An apparatus according to Claim 17, wherein said computer readable medium comprises at least one of a magnetic diskette, magnetic tape, a CD-ROM, a random access memory chip, and a read-only computer memory chip.
 - 19. An apparatus comprising a computer readable medium having encoded thereon computer-executable process steps, said process steps for detecting defects in a reticle used in integrated circuit chip fabrication, said process steps comprising steps to:
 - (a) obtain digital image data corresponding to an image of a reticle;
 - (b) process the digital image data according to predetermined criteria to identify defects;
 - (c) specify a window around one of the defects identified in step (b); and
- (d) simulate a response that would be produced if the window specified in step
 (c) were to be utilized in a photo ithographic system, by processing digital image data corresponding to the window specified in step (c).

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- 20. An apparatus according to Claim 19, wherein said computer readable medium comprises at least one of a magnetic diskette, magnetic tape, a CD-ROM, a random access memory chip, and a read-only computer memory chip.
- 21. An apparatus for detecting defects in a reticle used in integrated circuit chip fabrication, said apparatus comprising:

a processor for executing stored program instruction steps; and

a memory connected to the processor for storing the program

5 instruction steps,

wherein the program instruction steps include steps to:

- (a) obtain digital image data corresponding to an image of a reticle:
- (b) process the digital image data according to predetermined criteria to identify defects; and
- (c) simulate a response that would be produced if the reticle were to be utilized in a photolithographic system, by processing the digital image data corresponding to the reticle.
- 22. An apparatus for detecting defects in a reticle used in integrated circuit chip fabrication, said apparatus comprising:

a processor for executing stored program instruction steps; and

a memory connected to the processor for storing the program

5 instruction steps,

wherein the program instruction steps include steps to:

- (a) obtain digital image data corresponding to an image of a reticle;
- (b) process the digital image data according to predetermined criteria to identify defects;
- (c) specify a window around one of the defects identified in step(b); and

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(d) simulate a response that would be produced if the window specified in step (c) were to be utilized in a photolithographic system, by processing digital image data corresponding to the window specified in step (c).